

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	6	257/778.ccls. and (chip die IC (integrated adj circuit) (electronic adj component)) with arcuate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/05 18:51
L2	2	438/108.ccls. and (chip die IC (integrated adj circuit) (electronic adj component)) with arcuate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/05 18:51
L4	2	438/108.ccls. and (chip die IC (integrated adj circuit) (electronic adj component)) with arcuat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/05 18:51
L5	6	257/778.ccls. and (chip die IC (integrated adj circuit) (electronic adj component)) with arcuat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/05 18:51
L6	209	(chip die IC (integrated adj circuit) (electronic adj component)) with arcuat\$4 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/05 19:01
L8	401	(chip die IC (integrated adj circuit) (electronic adj component)) with (arcuat\$4 non-planar dom\$4) near2 surface and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/05 19:37
L10	6	438/108.ccls. and (chip die IC (integrated adj circuit) (electronic adj component)) with (arcuat\$4 non-planar dom\$4) near2 surface and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/05 19:38
L11	11	257/778.ccls. and (chip die IC (integrated adj circuit) (electronic adj component)) with (arcuat\$4 non-planar dom\$4) near2 surface and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/05 19:45
L12	1	438/618,666.ccls. and (chip die IC (integrated adj circuit) (electronic adj component)) with (arcuat\$4 non-planar dom\$4) near2 surface and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/05 19:39

L14	2	438/612.ccls. and (chip die IC (integrated adj circuit) (electronic adj component)) with (arcuat\$4 non-planar dom\$4) near2 surface and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/05 19:46
L15	5	438/613.ccls. and (chip die IC (integrated adj circuit) (electronic adj component)) with (arcuat\$4 non-planar dom\$4) near2 surface and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/05 19:46
L16	1	438/618.ccls. and (chip die IC (integrated adj circuit) (electronic adj component)) with (arcuat\$4 non-planar dom\$4) near2 surface and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/05 19:47
L19	1	438/122.ccls. and (chip die IC (integrated adj circuit) (electronic adj component)) with (arcuat\$4 non-planar dom\$4) near5 surface and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/05 19:47
L20	8	438/108.ccls. and (chip die IC (integrated adj circuit) (electronic adj component)) with (arcuat\$4 non-planar dom\$4) near5 surface and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/05 19:48
L21	0	438/666.ccls. and (chip die IC (integrated adj circuit) (electronic adj component)) with (arcuat\$4 non-planar dom\$4) near5 surface and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/05 19:48
L22	1	438/125.ccls. and (chip die IC (integrated adj circuit) (electronic adj component)) with (arcuat\$4 non-planar dom\$4) near5 surface and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/05 19:48
L23	1	438/122.ccls. and (chip die IC (integrated adj circuit) (electronic adj component)) with (arcuat\$4 non-planar dom\$4) near5 surface and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/05 19:49
L24	3	438/612.ccls. and (chip die IC (integrated adj circuit) (electronic adj component)) with (arcuat\$4 non-planar dom\$4) near5 surface and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/05 19:49
L25	5	438/613.ccls. and (chip die IC (integrated adj circuit) (electronic adj component)) with (arcuat\$4 non-planar dom\$4) near5 surface and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/05 19:49